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Listing of Claims

The following listing of claims will replace all prior versions, and listings, of claims in the subject application:

1. (currently amended) A heat-sensitive stencil sheet having a porous resin layer provided on one side of a thermoplastic resin film, and a porous fiber layer bonded by an adhesive to the surface of the porous resin layer, wherein the amount of the adhesive ranges from 0.05 g/m² to 1.5 g/m², and the bonding strength between the porous resin layer and the porous fiber layer ranges from 0.8 N/m to 50.0 N/m,

wherein the porous resin layer includes a multiplicity of walls and ceilings which define cells, and

wherein said adhesive bonding said porous fiber layer to said cell ceilings are bonded to the porous fiber layer by the adhesive has a viscosity of 300 cps or higher.

Claim 2 (canceled).

3. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein the adhesive is a primarily adhesive of ionizing radiation-curable type.

4. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous resin layer ranges from 0.5 g/m² to 10.0 g/m² by dry basis.

5. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of

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the porous resin layer ranges from 1.0 g/m² to 5.0 g/m² by dry basis.

6. (original) A heat-sensitive stencil sheet according to claim 1, wherein the porous resin layer is a foamy film formed by applying a fluid containing an resin emulsion of water in oil type onto a thermoplastic film and drying it.

7. (original) A heat-sensitive stencil sheet according to claim 1, wherein amount of the porous fiber layer ranges from 1.0 g/m² to 15.0 g/m².

8. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous fiber layer ranges from 3.0 g/m² to 10.0 g/m².

Claim 9-13 (canceled).

14. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous resin layer have an average diameter in a range of 5 μ m to 20 μ m.

Claim 15 (canceled).

16. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous fiber layer have an average diameter in a range of 25 μ m to 60 μ m.

17. (currently amended) A heat-sensitive stencil sheet having a porous resin layer

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provided on one side of a thermoplastic resin film, and a porous fiber layer bonded by an adhesive to the surface of the porous resin layer,

wherein the porous resin layer includes a multiplicity of walls and ceilings which define cells, and

wherein said adhesive bonding said porous fiber layer to said cell ceilings are bonded to the porous fiber layer by the adhesive has a viscosity of 300 cps or higher.

Claim 18 (canceled).

19. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous fiber layer are connected in a depth direction and to a lesser degree in a transverse direction, so that sideward deviated penetration of ink in the stencil sheet is decreased.

20. (previously presented) A heat-sensitive stencil sheet according to claim 17, wherein said adhesive bonding said porous fiber layer to said porous resin layer includes a polymer having radical polymeric double-bonds and containing mono-functional monomer or multi-functional monomer having relatively low molecular weight and are radically reactive with (meth)acrylates.

21. (previously presented) A heat-sensitive stencil sheet according to claim 20, wherein said adhesive further includes a photo-polymerization initiator.

22. (previously presented) A heat-sensitive stencil sheet according to claim 17, wherein said adhesive bonding said porous fiber layer to said porous resin layer includes a urethane

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acrylate oligomer.

23. (previously presented) A heat-sensitive stencil sheet according to claim 17, wherein said adhesive bonding said porous fiber layer to said porous resin layer is an ionizing radiation-curable type adhesive cured by applying ionizing radiation ray from the porous fiber layer side.

24. (previously presented) A heat-sensitive stencil sheet according to claim 17, wherein said adhesive bonding said porous fiber layer to said porous resin layer is an ionizing radiation-curable type adhesive cured by applying an electron beam.

Claim 25 (canceled).